

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $\pi$ -MOSV)**2SK3462**

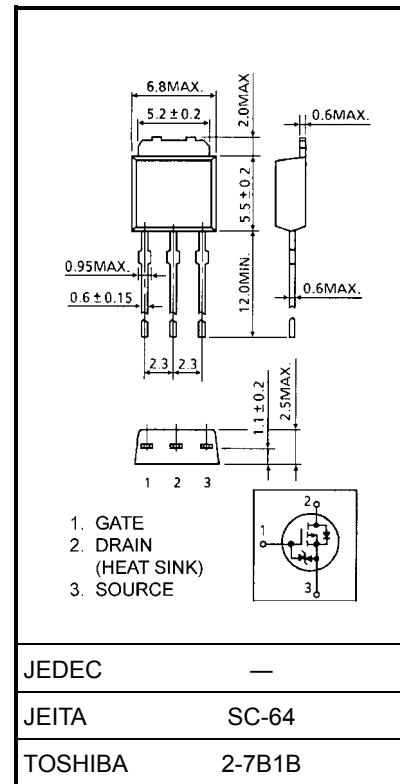
Switching Regulator, DC-DC Converter and  
Motor Drive Applications

Unit: mm

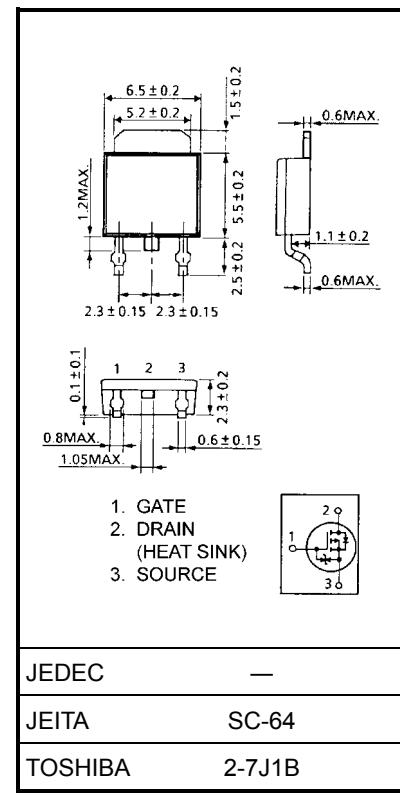
- 4 V Gate drive
- Low drain-source ON resistance:  $R_{DS\ (ON)} = 1.2\ \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 2.2\ S$  (typ.)
- Low leakage current:  $I_{DSS} = 100\ \mu A$  ( $V_{DS} = 250\ V$ )
- Enhancement-mode:  $V_{th} = 1.5\sim 3.5\ V$  ( $V_{DS} = 10\ V$ ,  $I_D = 1\ mA$ )

**Maximum Ratings (Ta = 25°C)**

Characteristics	Symbol	Rating	Unit
Drain-source voltage	$V_{DSS}$	250	V
Drain-gate voltage ( $R_{GS} = 20\ k\Omega$ )	$V_{DGR}$	250	V
Gate-source voltage	$V_{GSS}$	$\pm 20$	V
Drain current	DC (Note 1) Pulse ( $t = 1\ ms$ ) (Note 1)	$I_D$ $I_{DP}$	3 6
			A
Drain power dissipation ( $T_c = 25^\circ C$ )	$P_D$	20	W
Single pulse avalanche energy (Note 2)	$E_{AS}$	36.2	mJ
Avalanche current	$I_{AR}$	3	A
Repetitive avalanche energy (Note 3)	$E_{AR}$	2	mJ
Channel temperature	$T_{ch}$	150	°C
Storage temperature range	$T_{stg}$	-55~150	°C



Weight: 0.36 g (typ.)



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**Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th\ (ch-c)}$	6.25	°C/W
Thermal resistance, channel to ambient	$R_{th\ (ch-a)}$	125	°C/W

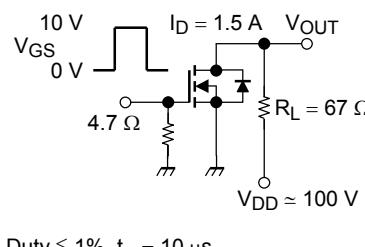
Note 1: Please use devices on conditions that the channel temperature is below 150°C.

Note 2:  $V_{DD} = 50\ V$ ,  $T_{ch} = 25^\circ C$ ,  $L = 6.7\ mH$ ,  $I_{AR} = 3\ A$ ,  $R_G = 25\ \Omega$

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.

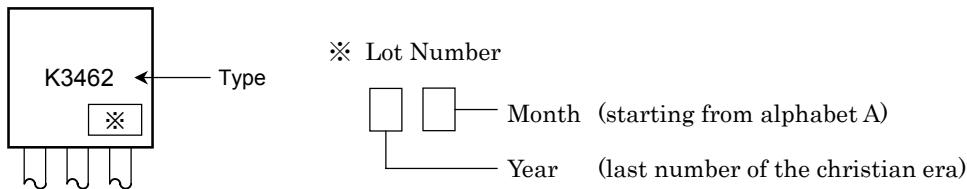
Electrical Characteristics ( $T_a = 25^\circ C$ )

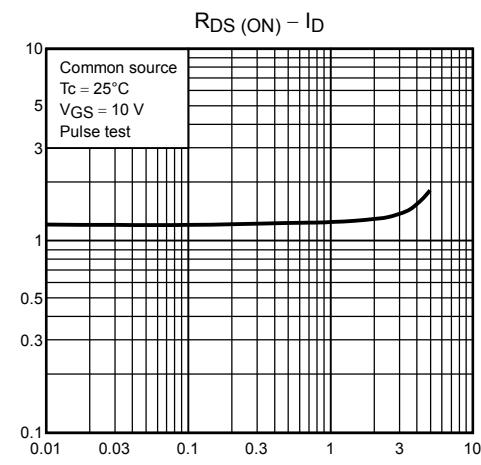
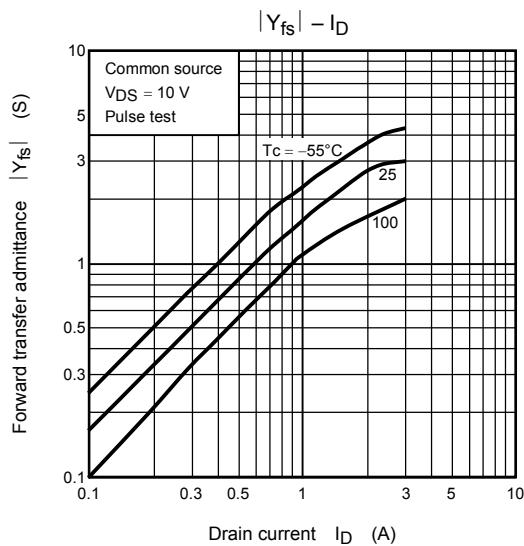
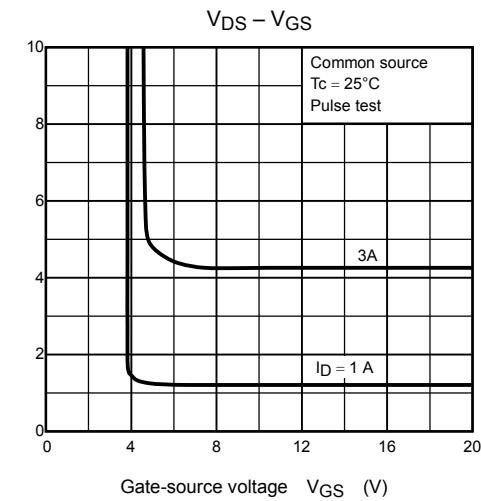
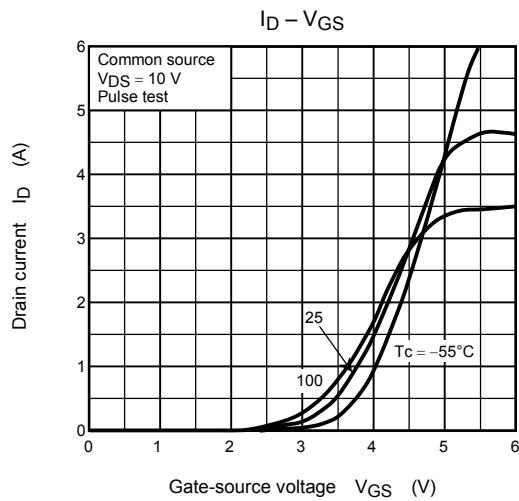
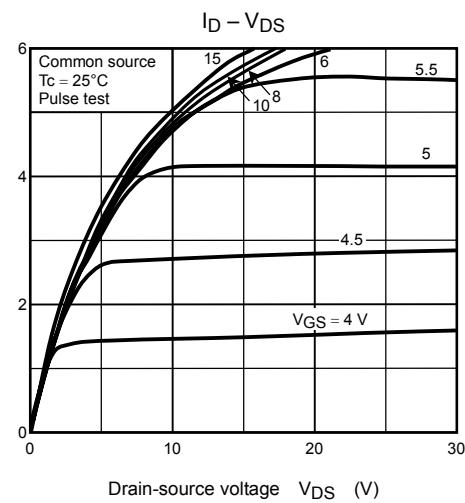
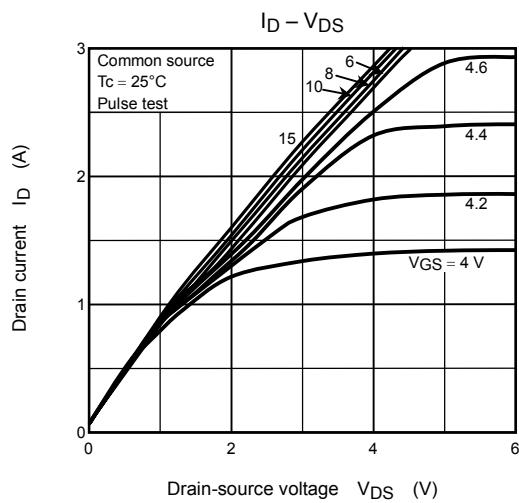
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit	
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 16 V, V_{DS} = 0 V$	—	—	$\pm 10$	$\mu A$	
Drain cut-off current	$I_{DSS}$	$V_{DS} = 250 V, V_{GS} = 0 V$	—	—	100	$\mu A$	
Drain-source breakdown voltage	$V_{(BR) DSS}$	$I_D = 10 mA, V_{GS} = 0 V$	250	—	—	V	
Gate threshold voltage	$V_{th}$	$V_{DS} = 10 V, I_D = 1 mA$	1.5	—	3.5	V	
Drain-source ON resistance	$R_{DS (\text{ON})}$	$V_{GS} = 10 V, I_D = 1.5 A$	—	1.2	1.7	$\Omega$	
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 10 V, I_D = 1.5 A$	0.5	2.2	—	S	
Input capacitance	$C_{iss}$	$V_{DS} = 10 V, V_{GS} = 0 V, f = 1 \text{ MHz}$	—	267	—	pF	
Reverse transfer capacitance	$C_{rss}$		—	32	—		
Output capacitance	$C_{oss}$		—	98	—		
Switching time	Rise time	$t_r$	 $V_{GS}$ 10 V $V_{GS}$ 0 V $I_D = 1.5 A$ $V_{OUT}$ $4.7 \Omega$ $R_L = 67 \Omega$ $V_{DD} \approx 100 V$ Duty $\leq 1\%$ , $t_W = 10 \mu s$	—	5	—	ns
	Turn-on time	$t_{on}$		—	20	—	
	Fall time	$t_f$		—	5	—	
	Turn-off time	$t_{off}$		—	30	—	
Total gate charge	$Q_g$	$V_{DD} \approx 200 V, V_{GS} = 10 V, I_D = 3 A$	—	12	—	nC	
Gate-source charge	$Q_{gs}$		—	6	—		
Gate-drain charge	$Q_{gd}$		—	6	—		

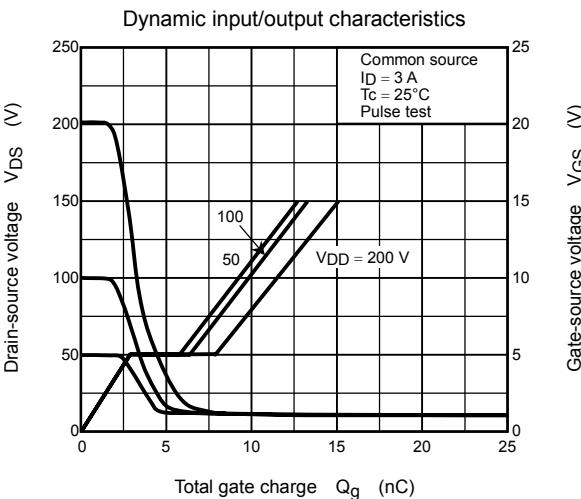
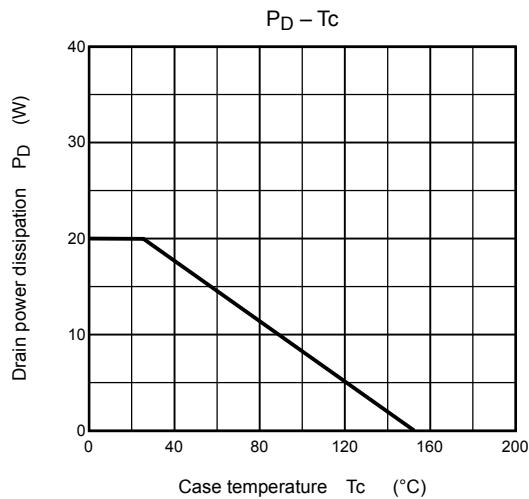
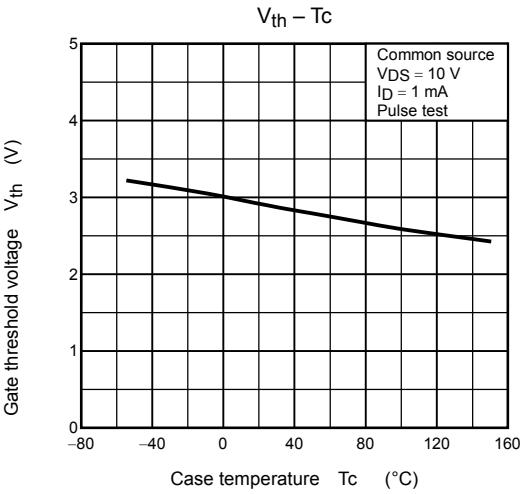
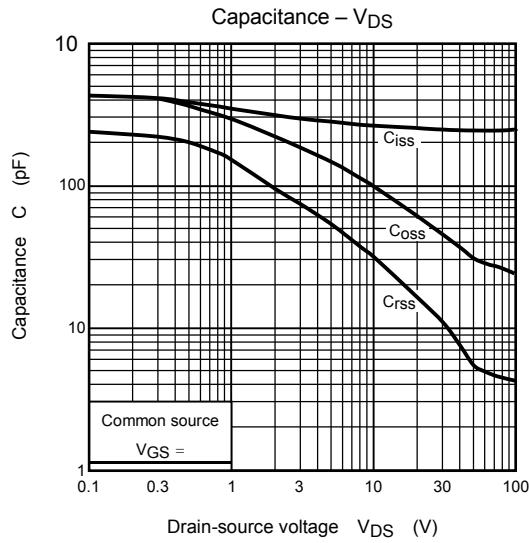
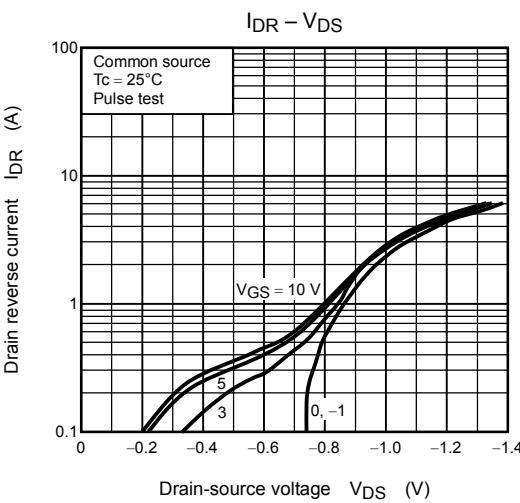
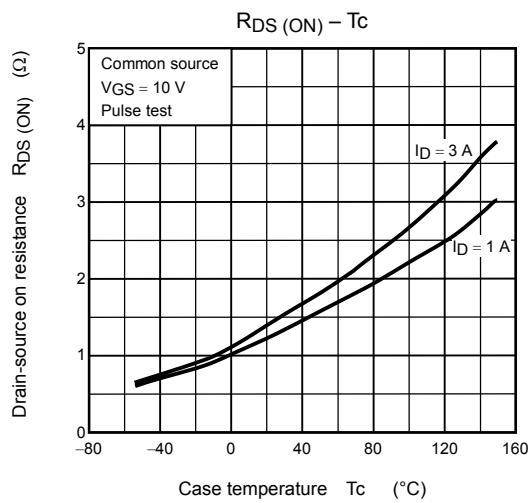
Source-Drain Ratings and Characteristics ( $T_a = 25^\circ C$ )

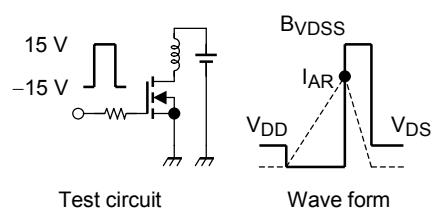
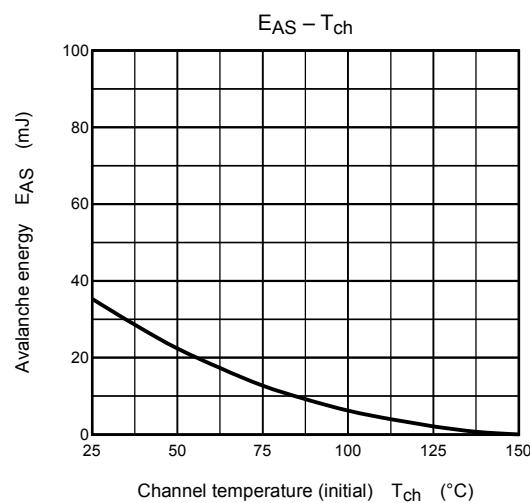
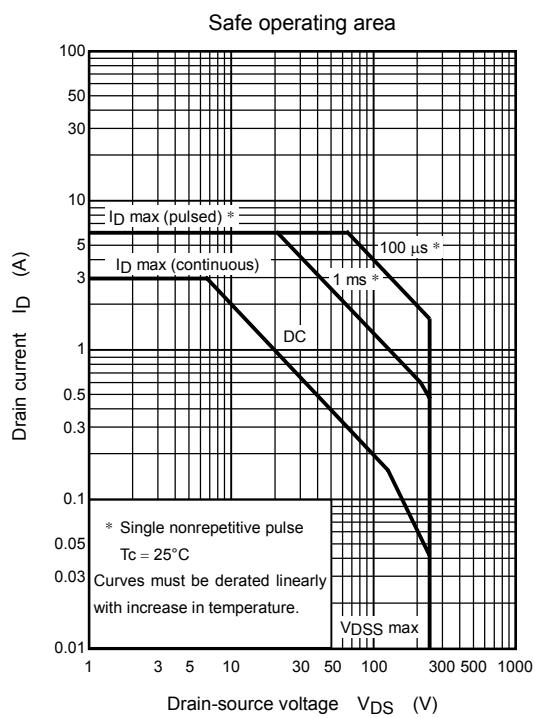
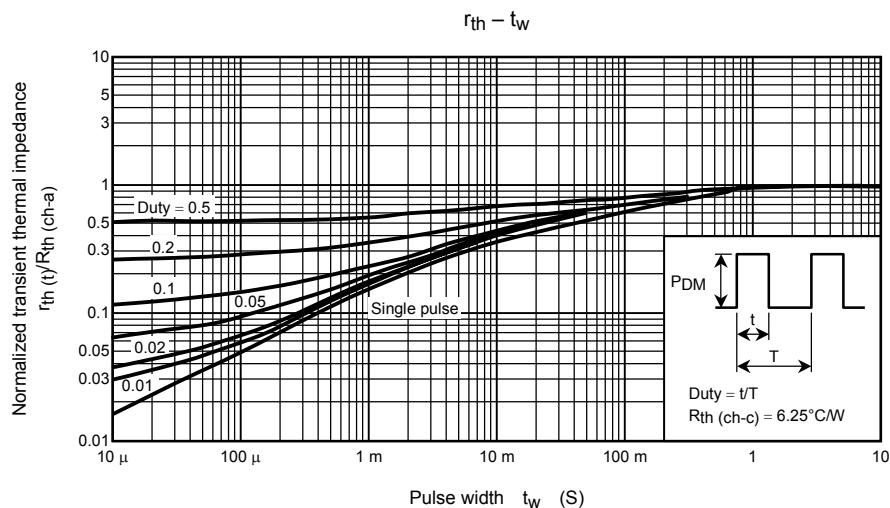
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	$I_{DR}$	—	—	—	3	A
Pulse drain reverse current (Note 1)	$I_{DRP}$	—	—	—	6	A
Forward voltage (diode)	$V_{DSF}$	$I_{DR} = 3 A, V_{GS} = 0 V$	—	—	-2.0	V
Reverse recovery time	$t_{rr}$	$I_{DR} = 3 A, V_{GS} = 0 V,$ $dI_{DR}/dt = 100 A/\mu s$	—	125	—	ns
Reverse recovery charge	$Q_{rr}$		—	470	—	nC

## Marking









$$R_G = 25 \Omega$$

$$V_{DD} = 50 \text{ V}, L = 6.7 \text{ mH}$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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